22nd European Wet & 51st European CMP User Group Meeting

Wet- and CMP-Session: Thursday, October 29, 2026, 12:00 – 18:10

CMP-Session: Friday, October 30, 2026, 8:30 – 13:15

Dresden Airport, Dresden, Germany

Organized by European CMP&WET User Group

Agenda Thursday, October 29th

12:00 – 13:30 Welcome Coffee, Tea, Softdrinks and Snacks

13:30 Opening Remarks & Welcome
Knut Gottfried
Fraunhofer ENAS & ErzM-Technologies, Chemnitz, Germany

Wet Session 1

Session Chair: Knut Gottfried, Fraunhofer ENAS & ErzM-Technologies, Chemnitz, Germany

13:40 Improving TTV in Wet Chemical Thinning Through Integrated Metrology
James Welsh and Martin Huber
NexGen Wafer System, Villach, Austria

14:05 Aqueous HF-ClO_2 mixtures: A Promising Alternative to HF-HNO_3 Solutions for Wet Chemical Etching of Silicon
Niklas Zomack, André Stapf and Edwin Kroke
TU Bergakademie Freiberg, Germany

14:20 Non-Contact Eddy-Current Sensor Concepts for in-tool Monitoring to Maximize Product Quality Output
Marcus Klein, Michael Hofmann and Markus Stärz
Suragus GmbH, Dresden, Germany

14:35 Process Control of Electroplating Processes in the Semiconductor Industry: Requirements and Approaches
Norbert Schröder
Fraunhofer IZM-ASSID, Moritzburg, Germany

15:00 Si-BrOzone - Etching Silicon in HF-Br_2 Mixtures and Regeneration with O_3
André Stapf, Niklas Zomack, Nils Schubert and Edwin Kroke
TU Bergakademie Freiberg, Germany

15:15 Company Pitch
ProSys, Gold Sponsor
Igor Eichinger, ProSys, Campbell, CA, USA

15:20 Coffee Break

Wet Session 2 & CMP Session 1

Session Chair: Gerfried Zwicker, zwickerconsult, Berlin, Germany

16:05 NanoLPM: Particle Characterization from Ultrapure Liquids to Slurries
Torben Rüther
TSI GmbH, Aachen, Germany

16:30 Moving Beyond Contact: Interfacial and Tribochemical Approaches to Low-Stress Post-CMP Cleaning
Jason Keleher
Lewis University, Romeoville, IL, USA

17:00 Chemical Mechanical Planarization as Enabler for Advanced Packaging & Quantum Devices
Gul Bahar Basim
SkyWater Technology, Kissimmee, FL, USA

17:45 Copper CMP Solutions for Advanced Packaging
Federico Barbieri
Entegris GmbH, Dresden, Germany

18:10 End of Wet User Group Meeting / Time for networking and discussion

19:00 Evening Reception and Dinner at Dresden Airport

22:00 End of Day 1

Agenda Friday, October 30th

8:30 – 9:00 Good Morning Coffee, Tea, Softdrinks

9:00 Opening Remarks
Gerfried Zwicker
zwickerconsult, Berlin, Germany

CMP Session 2

Session Chair: Martin Kulawski, Advaplan, Espoo, Finland

09:05 Vibration Studies on a 300mm CMP Polisher
Len Borucki and Ara Philipossian
Araca Inc., Tucson, AZ, USA

09:40 Reliable LPC and D50 Characterization of CMP Slurries by Single Particle Light Scattering
Matthew A. Hood, Holger Woehlecke and Elia Wollik
LUM GmbH, Berlin, Germany
20 min CMP Product Pres.

10:05 From Pattern Density Optimization to Planarization: Oxide CMP Development for PIC Bonding
Nagesh Bhat, MeiRu Su and Tomasso Cassese
Silicon Austria Labs GmbH, Villach, Austria

10:20 Fabrication And Characterization of High-Quality Nb/Al-AlO /Nb Cross-Type Josephson Tunnel Junctions Utilising CMP-based Planarisation Techniques
Alexander Stoll, Andreas Reifenberger, Daniel Hengstler, Andreas Fleischmann and Christian Enss
Kirchhoff-Institute for Physics (KIP), Heidelberg University, Germany

10:35 Highlights from ICPT 2026
Gerfried Zwicker
zwickerconsult, Berlin, Germany

10:50 Company Pitch
Ebara, Gold Sponsor
Alain Chabourel, Ebara Precision Machinery Europe, Hanau, Germany

10:55 **Coffee Break**

CMP Session 3

Session Chair: Catharina Rudolph, Fraunhofer IZM-ASSID, Dresden, Germany

11:40 Impact of Slurry Flow Patterns on CMP Process Tribology and Likely Removal Rate Consequences
Ara Philipossian, Len Borucki, Garegin Mazmanyan, Ali Mardi, Siannie Theng and Yasa Sampurno
Araca Inc., Tucson, AZ, USA

12:15 Selective Fines Removal in CMP Slurries: Filtration and Wafer Results
Günter Haas
Entegris, Moirans, France

12:30 Leveraging Nanoparticle Chemistry Synergies as a Pathway for Self-Cleaning CMP Processes
Jason Keleher
Lewis University, Romeoville, IL, USA

13:00 R2R Prediction of CMP Polish Time for Increased Material Throughput
Joerg Reichelt
ONTO Innovation, Dresden, Germany

13:15 End of CMP User Group Meeting / Time for Networking and Discussion

Coffee, Tea, Softdrinks, and Light Lunch